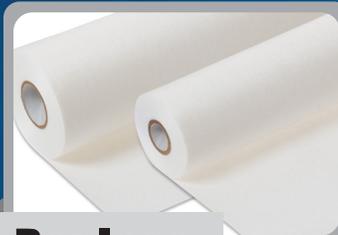# 5 Steps to Reducing Solder Paste Defects

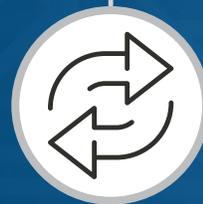## Plan
cleaning BEFORE printing

1

MicroCare Applications Experts can help you engineer your SMT process to achieve perfectly clean solder stencils even before production begins. Choose the profile, tooling, equipment, process AND SPECIFY the cleaning options first.

Replace
abrasive cellulose-based roll wipes

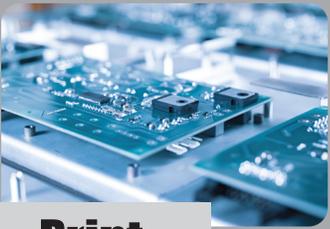**2**

Switch to softer, durable and absorbent *Fine Pitch Fabric Stencil Rolls* from MicroCare. With no glues or binders to dissolve, they reduce FOD in your machines from high linting paper rolls.

MicroCare™
Discover Perfectly Clean

5 Steps to Reducing Solder Paste Defects

Print
more panels between cleaning cycles

Clean
faster with no soaking

Enjoy
the benefits of cleaner stencils

3

4

5

MicroCare Fine Pitch Fabric Stencil Rolls limit dry wipe frequency, increasing your throughput and delivering more boards per hour. The softer fabric extends the life of stencil nano coatings and improves stencil aperture cleaning with fewer stencil-caused defects.
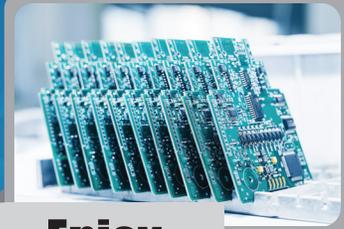
Use *MicroCare heavy-duty presaturated wipes* to clean stencils, squeegees, spatulas and tools. Choose IsoClean™ IPA-Based Wipes (BACW), ScreenClean™ Stencil & Squeegee Wipes (CDIW) or MultiClean™ MultiTask Surface Cleaner Wipes (MLCW). All are no-rip, non-linting and ESD-safe.

Improved print quality directly translates to fewer defects, less rework and fewer scrapped PCBs. Produce more boards-per-day at a *lower cost-per-board* to save time and money.

Experts say up to 65% of solder defects start at the printer.

Bridging, incomplete prints and paste left in apertures or vias are common defects caused by dirty stencils.

— **DID YOU KNOW?** —

Get Better Stencil Cleaning at

MicroCare.com

MicroCare™